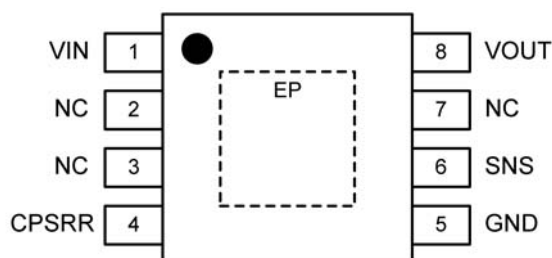


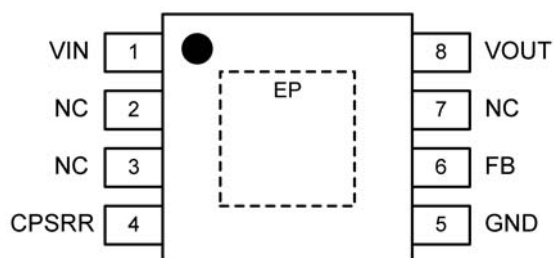
## Ordering Information

Part Number	Output Voltage	Top Mark	Temperature Range	Package	Lead Finish
MAQ5283YME	Adjustable	MAQ5283YME	−40°C to +125°C	8-Pin ePad SOIC	Pb-Free
MAQ5283-3.3YME	3.3V	MAQ5283-33YME	−40°C to +125°C	8-Pin ePad SOIC	Pb-Free
MAQ5283-5.0YME	5.0V	MAQ5283-50YME	−40°C to +125°C	8-Pin ePad SOIC	Pb-Free

## Pin Configuration



**8-Pin ePAD SOIC  
MAQ5283-x.xYME  
Fixed Voltage Output  
(TOP VIEW)**



**8-Pin ePAD SOIC  
MAQ5283YME  
Adjustable Voltage Output  
(TOP VIEW)**

## Pin Description

Pin Number		Name	Function
Adjustable Output	Fixed Output		
1	1	VIN	Supply Voltage Input. Connect 1μF capacitor from VIN to GND.
2, 3, 7	2, 3, 7	NC	Not internally connected. Connect NC to GND or leave unconnected.
4	4	CPSRR	Bypass Capacitor Connection. Connect 0.1μF capacitor from CPSRR to GND.
5	5	GND	Ground.
6	—	FB	Feedback Connection. For external resistor divider to set $V_{OUT}$ .
—	6	SNS	Sense input. Connect SNS to VOUT.
8	8	VOUT	Regulator Output. Connect 10μF capacitor from VOUT to GND.
EP	EP	ePad	Exposed Pad (ePad) for Thermal Dissipation. Connect to GND.

**Absolute Maximum Ratings<sup>(1)</sup>**

$V_{IN}$ to GND.....	–0.3V to +125V
$V_{CPSRR}$ to GND.....	–0.3 to +14V
$V_{FB}$ , $V_{SNS}$ , $V_{OUT}$ to GND.....	–0.3V to +6V
Lead Temperature (soldering, 10s).....	+260°C
Junction Temperature.....	–40°C ≤ $T_J$ ≤ +125°C
Storage Temperature.....	–65°C ≤ $T_A$ ≤ +150°C
ESD Ratings <sup>(4)</sup>	
HBM.....	2kV
MM.....	200V

**Electrical Characteristics<sup>(5)</sup>**

$V_{IN}$  = 12V,  $C_{IN}$  = 1.0μF,  $C_{PSRR}$  = 0.1μF,  $C_{OUT}$  = 10μF,  $I_{OUT}$  = 100μA,  $T_J$  = 25°C, **bold** values indicate –40°C ≤  $T_J$  ≤ +125°C, unless noted.

Parameter	Condition	Min.	Typ.	Max.	Units
Power Supply Input					
Input Voltage Range		6		120	V
Quiescent Supply Current	I <sub>OUT</sub> = 0		8	14	μA
Output Voltage					
Output Voltage Accuracy	Variation from nominal V <sub>OUT</sub> 100μA ≤ I <sub>OUT</sub> ≤ 150mA	-5		+5	%
Line Regulation	V <sub>IN</sub> = 10V to 120V	−0.5	0.04	+0.5	%
Feedback Input (Adjustable)					
FB Voltage	100μA ≤ I <sub>OUT</sub> ≤ 150mA	1.167	1.228	1.289	V
FB Current			3.2		nA
Current Limit					
Current Limit	V <sub>OUT</sub> = 0V	180	300	500	mA
Ripple Rejection					
Power Supply Rejection Ratio	I <sub>OUT</sub> = 50mA	100Hz ≤ f ≤ 1kHz		70	dB
		1kHz < f ≤ 30kHz		75	dB
		30kHz < f ≤ 100kHz		65	dB
Power Dropout Voltage					
Dropout Voltage	I <sub>OUT</sub> = 150mA		1.8	2.8	V
Thermal Protection					
Thermal-Shutdown Temperature	T <sub>J</sub> rising		155		°C
Thermal-Shutdown Hysteresis			15		°C

**Notes:**

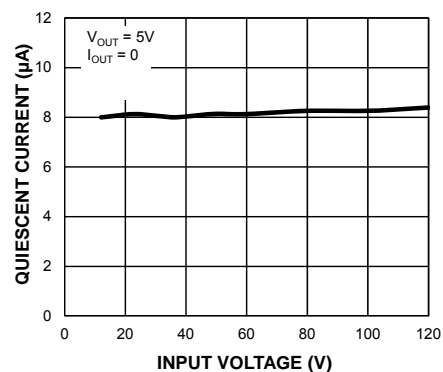
- Exceeding an absolute maximum rating may damage the device.
- The device is not guaranteed to function outside its operating rating.
- The maximum allowable power dissipation at any  $T_A$  (ambient temperature) is  $P_{D(max)} = (T_{J(max)} - T_A) / \theta_{JA}$ . Exceeding the maximum allowable power dissipation results in excessive die temperature, and causes the regulator to enter thermal shutdown.
- Devices are ESD sensitive; use proper handling precautions. Human body model, 1.5kΩ in series with 100pF.
- Specifications are for packaged products only.

**Operating Ratings<sup>(2)</sup>**

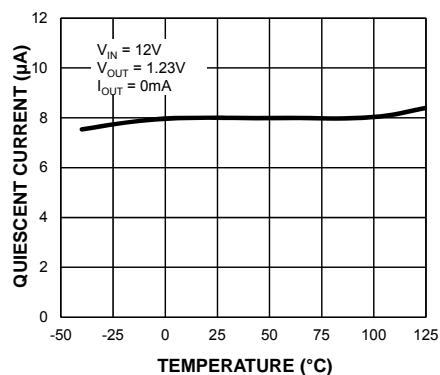
$V_{IN}$ .....	+6V to +120V
$V_{OUT}$ Adjust Range.....	+1.23V to +5.5V
Junction Temperature.....	–40°C ≤ $T_J$ ≤ +125°C
Power Dissipation ( $P_D$ ).....	Internally Limited <sup>(3)</sup>
Junction Thermal Resistance ( $\theta_{JA}$ )	
8-pin ePad SOIC.....	41°C/W

## Typical Characteristics

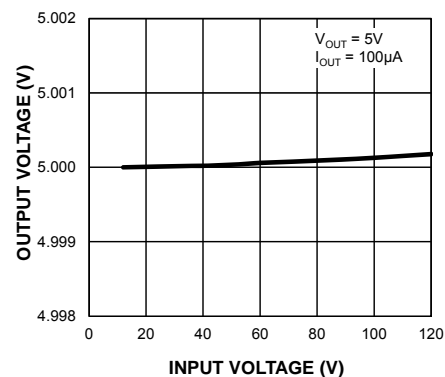
Quiescent Supply Current  
vs. Input Voltage



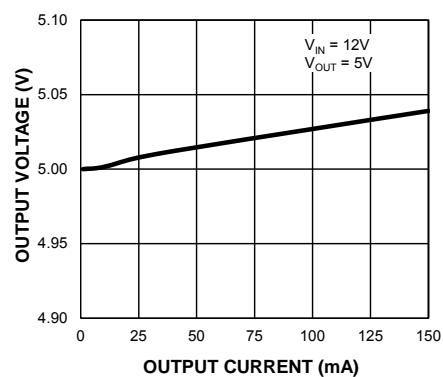
Quiescent Supply Current  
vs. Temperature



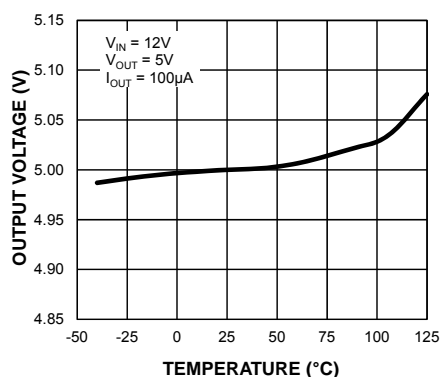
Output Voltage  
vs. Input Voltage



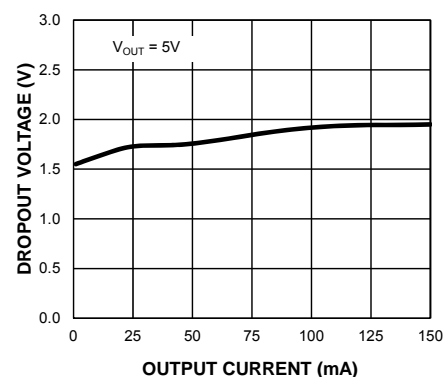
Output Voltage  
vs. Output Current



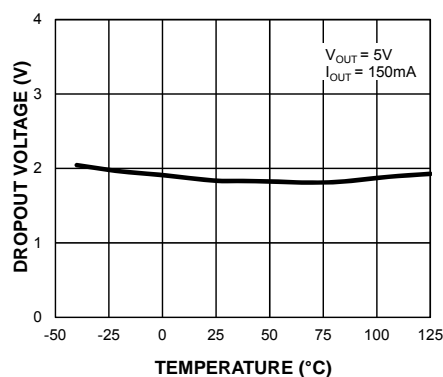
Output Voltage  
vs. Temperature



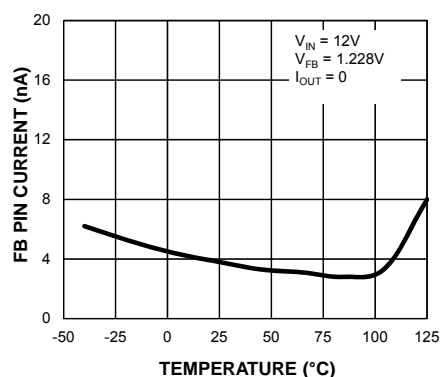
Dropout Voltage  
vs. Output Current



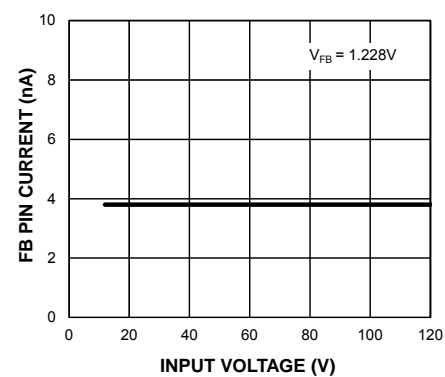
Dropout Voltage  
vs. Temperature



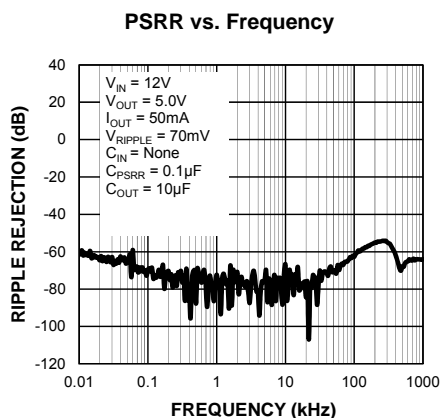
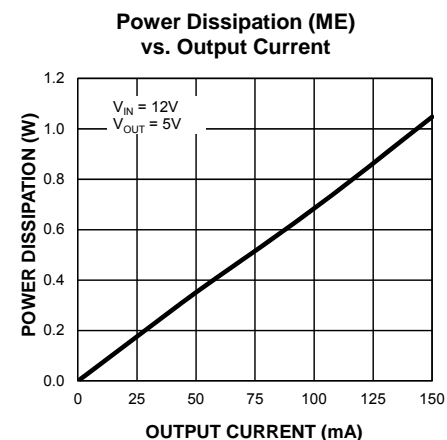
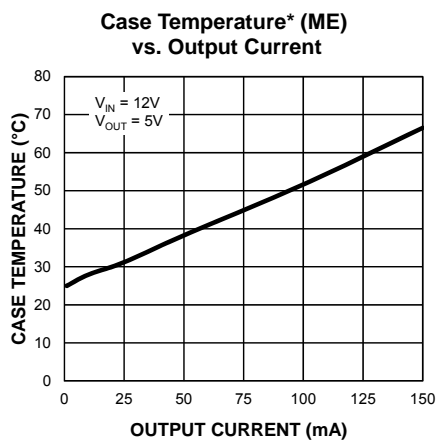
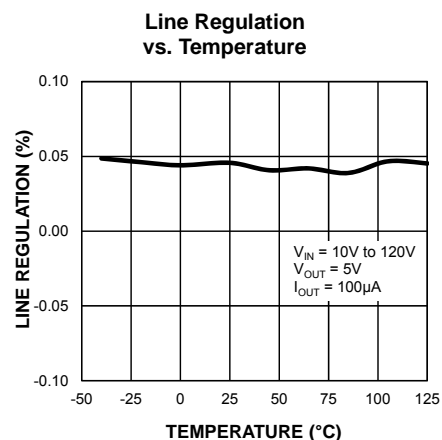
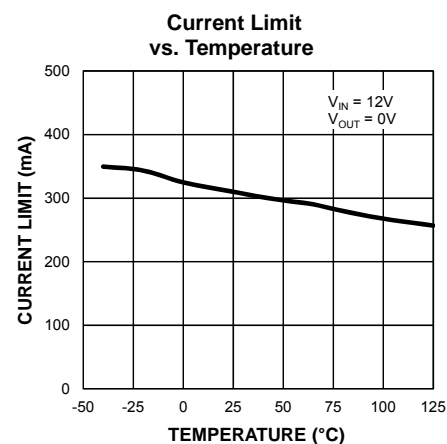
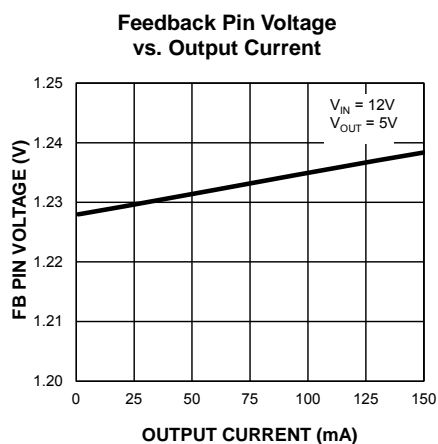
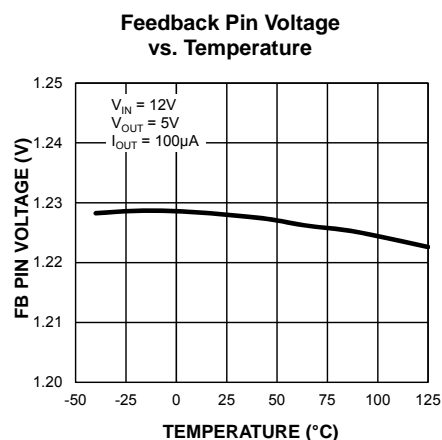
Feedback Pin Current  
vs. Temperature



Feedback Pin Current  
vs. Input Voltage



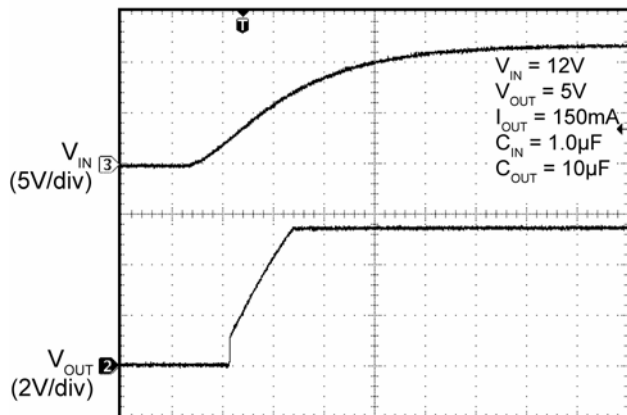
## Typical Characteristics (Continued)



**Case Temperature\*:** The temperature measurement was taken at the hottest point on the MAQ5283 case mounted on a 2.25-square-inch PCB at an ambient temperature of 25°C; see the [“Thermal Measurements”](#) section. Actual results depend on the size of the PCB, ambient temperature, and proximity to other heat emitting components.

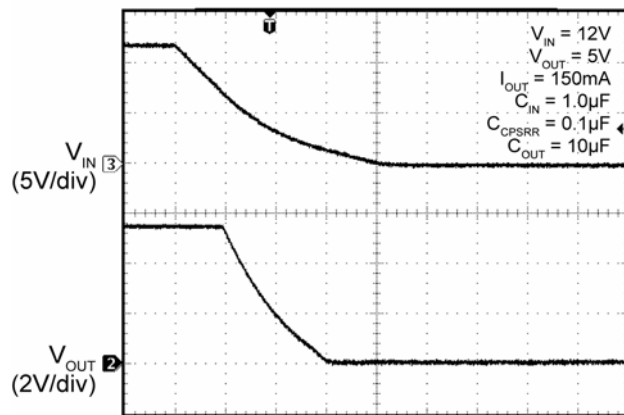
## Functional Characteristics

Soft Turn-On into Full Load



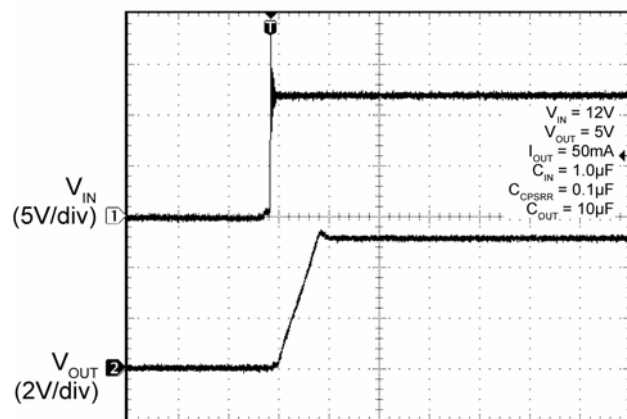
Time (2.0ms/div)

Soft Turn-Off



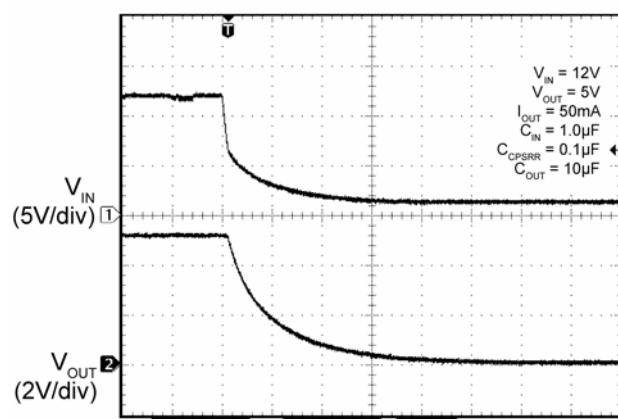
Time (10ms/div)

Fast Turn-On

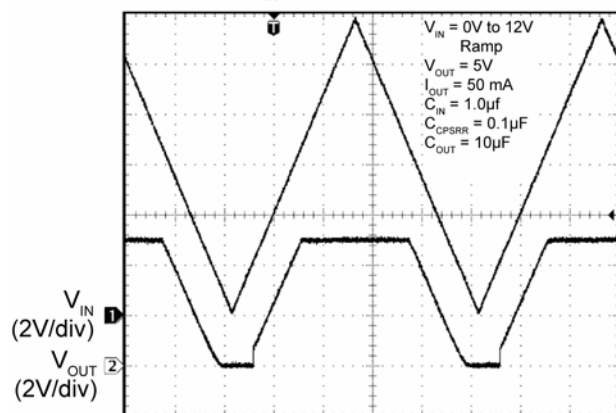


Time (200μs/div)

Fast Turn-Off

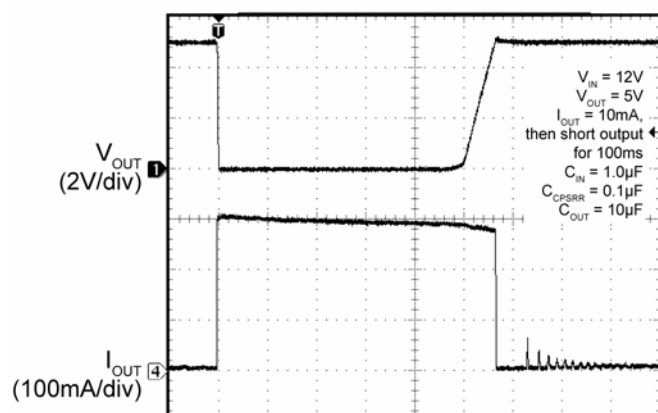


Time (1.00ms/div)

 $V_{IN}$  ULVO Threshold

Time (200ms/div)

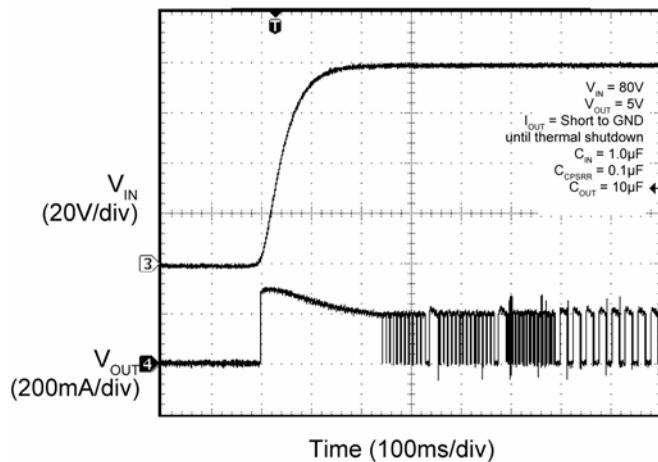
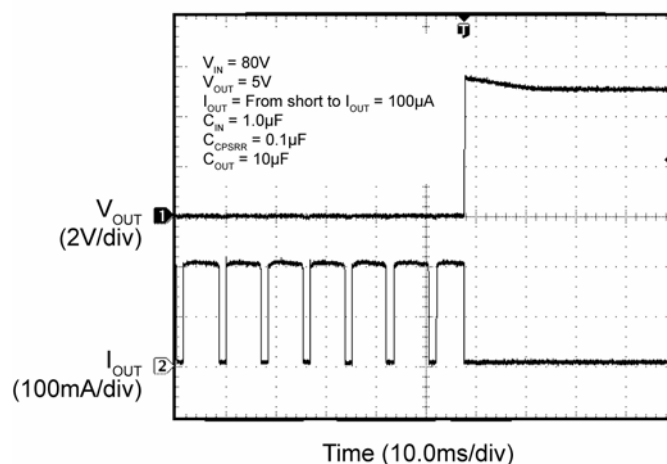
Current Limit



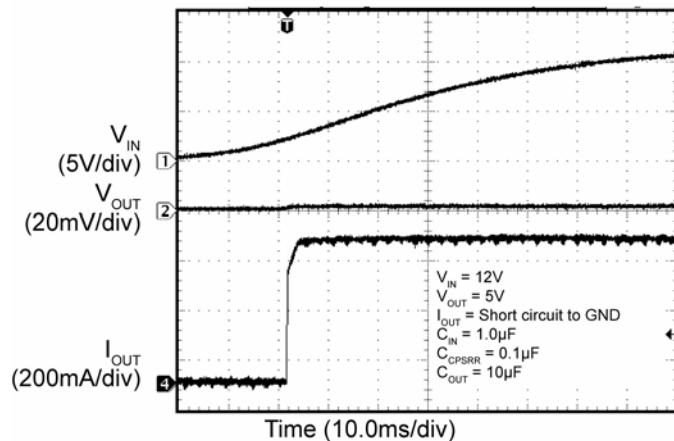
Time (20ms/div)

## Functional Characteristics (Continued)

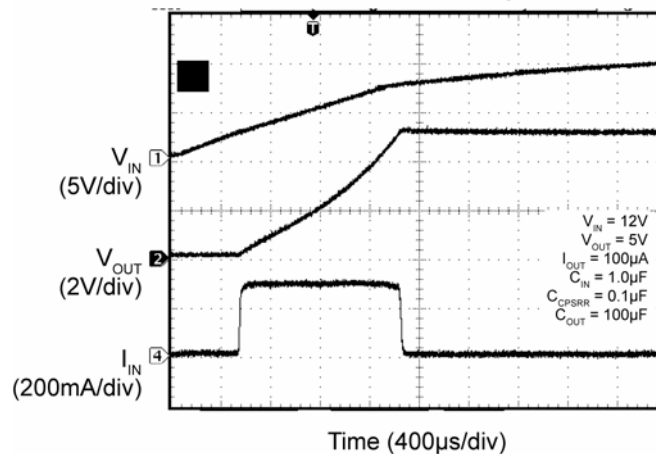
Thermal Shutdown Response

 $V_{OUT}$  Recovery from Thermal Shutdown

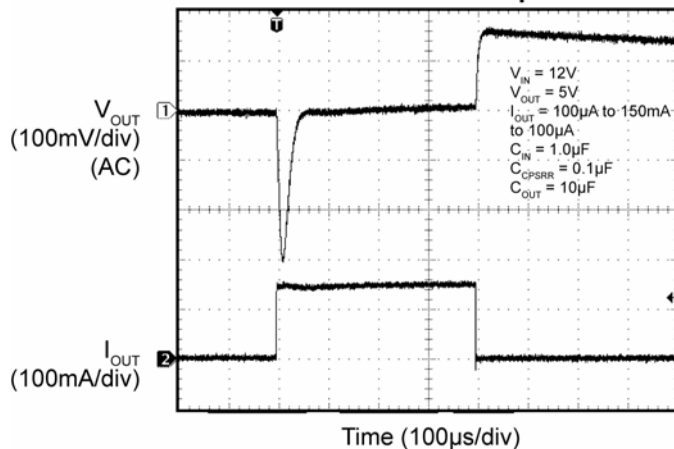
Turn-On into Short Circuit



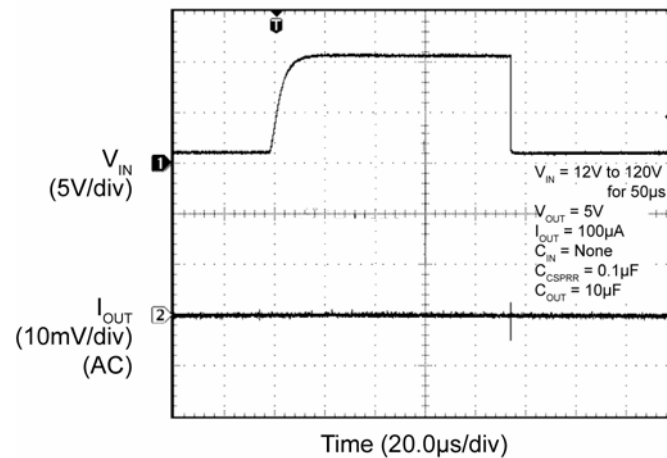
Inrush Current Response



Load Transient Response



Line Transient Response



## Detailed Description

The MAQ5283 voltage regulator accepts a 6V to 120V input voltage and has an ultra-low 8μA typical quiescent current while offering an excellent line transient response and PSRR. These features make it ideal for harsh, noisy environments. All options offer 150mA of output current. The MAQ5283YME offers an adjustable output voltage from 1.23V to 5.5V. The MAQ5283-3.3YME offers a fixed 3.3V output and the MAQ5283-5.0YME offers a fixed 5.0V output. The YME packaged devices feature a heat slug to remove heat from the die more effectively.

## Applications Information

### Thermal Protection

The MAQ5283 has internal thermal shutdown to protect it from excessive heating of the die. When the junction temperature exceeds approximately +155°C, the output is disabled and the device begins to cool down. The device turns back on when the junction temperature cools by 15°C. This results in a cycled output during continuous thermal-overload conditions.

### Current Limit

The MAQ5283 features output current-limit protection. The output sustains a continuous short circuit to GND without damage to the device, but thermal shutdown often results. The typical value for the current limit of the MAQ5283 is 300mA.

### Input Capacitor

Connect a 1.0μF capacitor from VIN to GND. Micrel recommends the C5750X7R2E105M, 1.0μF, 250V capacitor made by TDK. When using a different capacitor, make sure that the voltage rating of the capacitor has enough headroom to withstand any potential transient.

### CPSRR Capacitor

To maintain high power supply rejection, connect a 0.1μF capacitor from CPSRR to GND. The voltage rating of the capacitor must be at least 14V.

### Output Capacitor

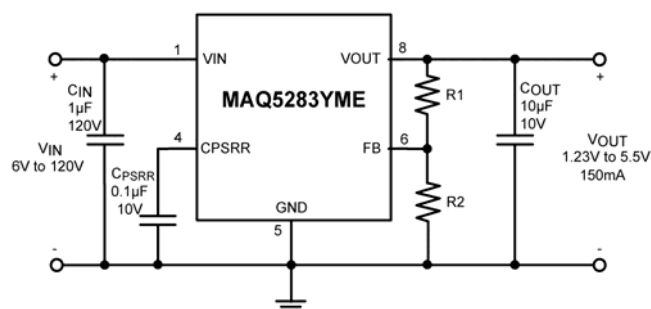
Connect a 10μF capacitor from VOUT to GND. Make sure that the voltage rating of the capacitor is greater than the designed output voltage of the MAQ5283.

## Output Voltage Setting

For the MAQ5283YME, V<sub>OUT</sub> is programmable from 1.23V to 5.5V using an external resistive divider. V<sub>OUT</sub> is set using the following equation:

$$V_{OUT} = V_{REF} \times \left( \frac{R1}{R2} + 1 \right) \quad \text{Eq. 1}$$

where V<sub>REF</sub> = 1.228V, and R1 and R2 form the feedback voltage divider from V<sub>OUT</sub> to ground.

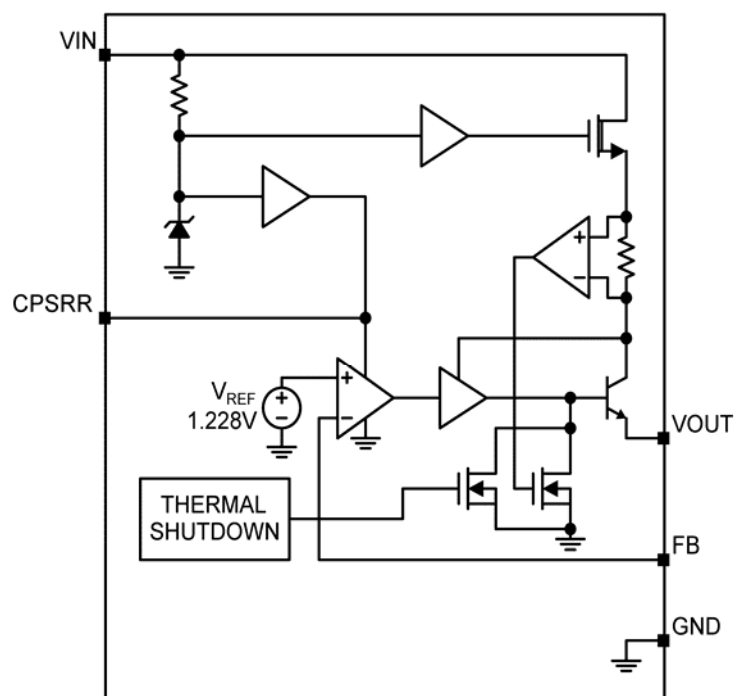


## Thermal Measurements

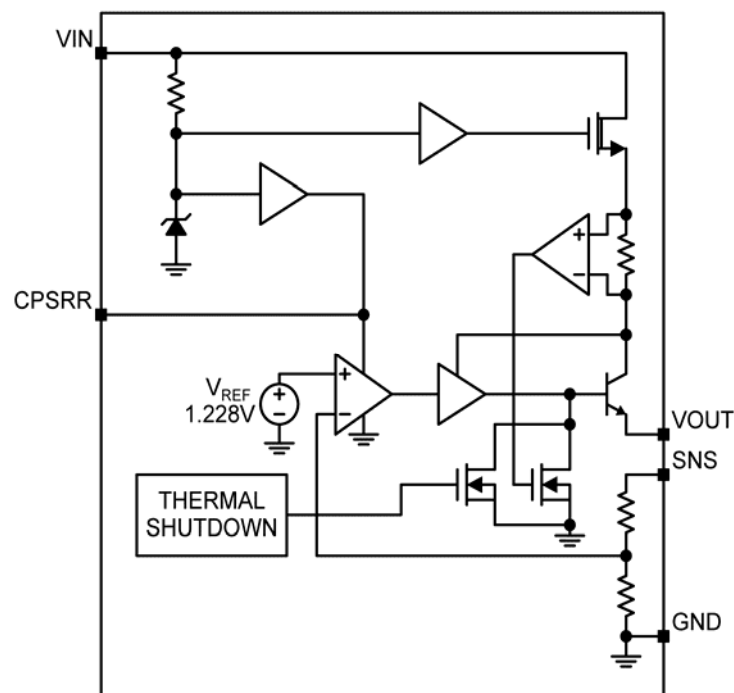
It is always a good idea to measure an IC's case temperature to make sure that it is within operating limits, but it is easy to get false results. The standard thermocouple that comes with many voltage meters uses a large wire gauge that behaves like a heat-sink. This causes artificially low case temperature measurements. Use a thermocouple of 36-gauge wire or smaller, such as the Omega (5SC-TT-K-36-36), to minimize the heat-sinking effect. Also, apply a thermal compound to maximize heat transfer between the IC and the thermocouple.

An infrared thermometer is a recommended alternative. The IR thermometer from Optris has a 1mm spot size, which is ideal for monitoring small surface-mount packages. Also, the optional stand makes it easy to keep the beam on the IC for long periods of time.

## Functional Diagram



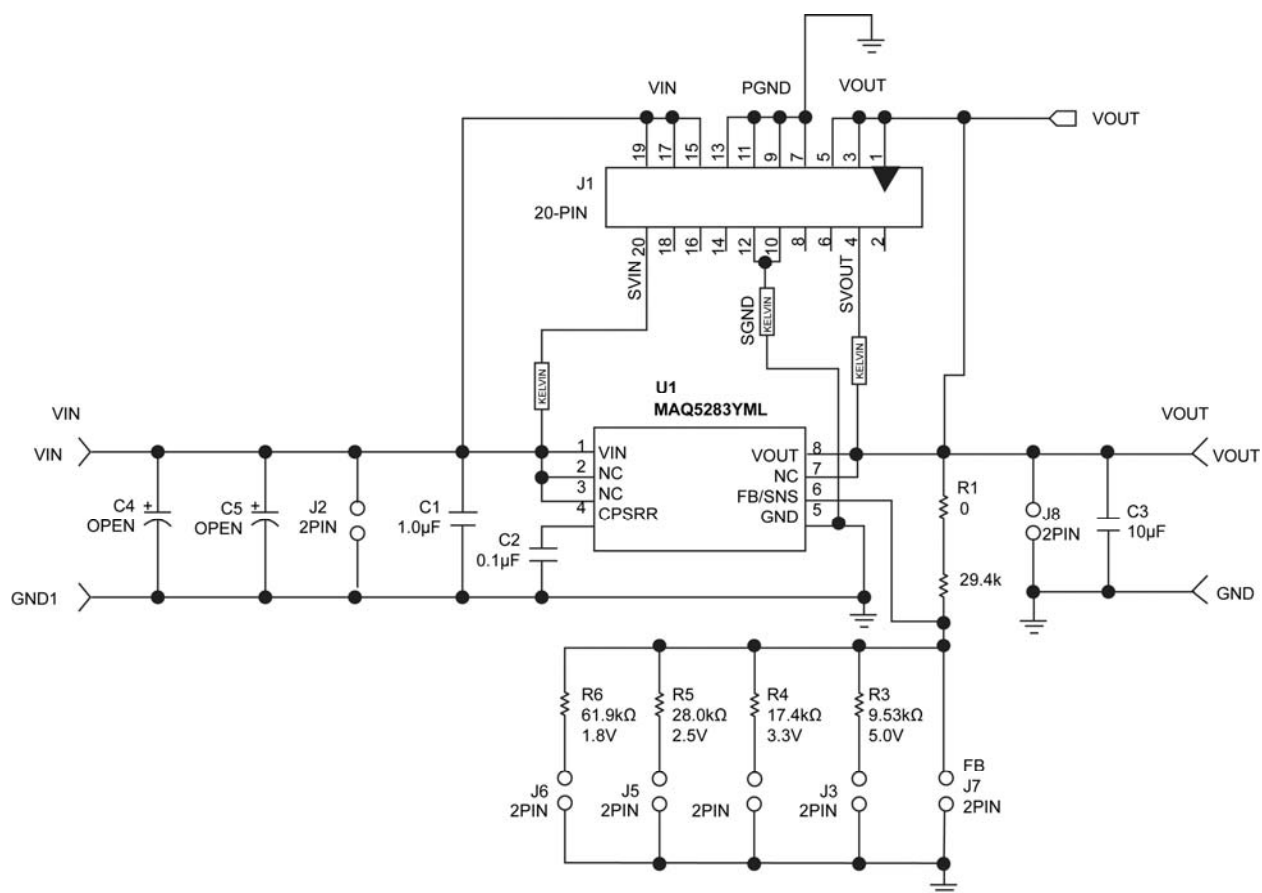
MAQ5283 Adjustable Version



MAQ5283 Fixed Version



## MAQ5283 Evaluation Board Schematic



MAQ5283 Evaluation Board Schematic

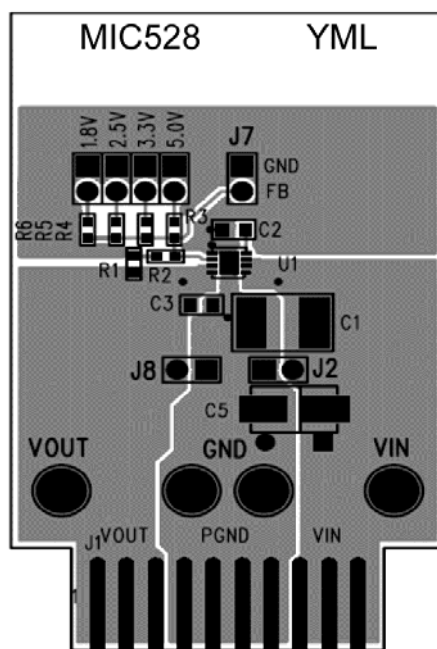
## Bill of Materials

Item	Part Number	Manufacturer	Description	Qty.
C1	C5750X7R2E105M	TDK <sup>(1)</sup>	1.0µF, 250V, 20%, X7R capacitor (2220)	1
C2	08053C104KAT2A	AVX <sup>(2)</sup>	0.1µF 25V 20%, X7R capacitor (0805)	1
C3	0805ZD106KAT2A	AVX	10µF, 10V, 20%, X5R, capacitor (0805)	1
R1	CRCW06030000F	Vishay/Dale <sup>(3)</sup>	0Ω, 1% resistor, 0603	1
R2	CRCW06032942F	Vishay/Dale	29.4kΩ, 1% resistor, 0603	1
R3	CRCW06039531F	Vishay <sup>(3)</sup>	9.53kΩ Film Resistor, Size 0603, 1%	1
R4	CRCW06031742F	Vishay	17.4kΩ Film Resistor, Size 0603, 1%	1
R5	CRCW06032802F	Vishay	28.0kΩ Film Resistor, Size 0603, 1%	1
R6	CRCW06036192F	Vishay	61.9kΩ Film Resistor, Size 0603, 1%	1
U1	MAQ5283YML	Micrel <sup>(4)</sup>	120V <sub>IN</sub> , 150mA, Ultra-Low I <sub>Q</sub> , High-PSRR Linear Regulator	1

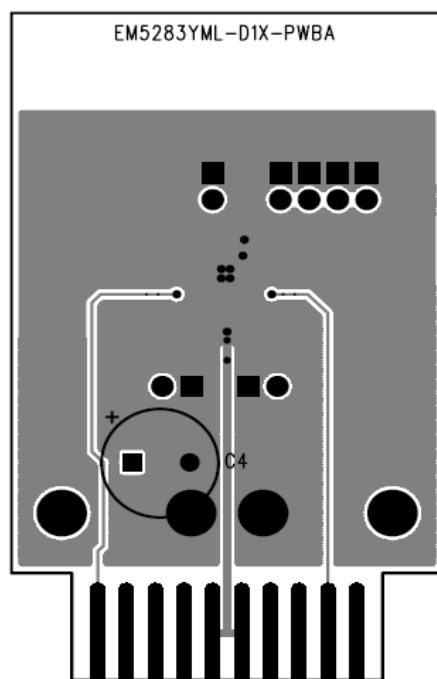
### Notes:

1. TDK: [www.tdk.com](http://www.tdk.com).
2. AVX: [www.avx.com](http://www.avx.com).
3. Vishay Tel: [www.vishay.com](http://www.vishay.com).
4. Micrel, Inc.: [www.micrel.com](http://www.micrel.com).

## PCB Evaluation Board Layout

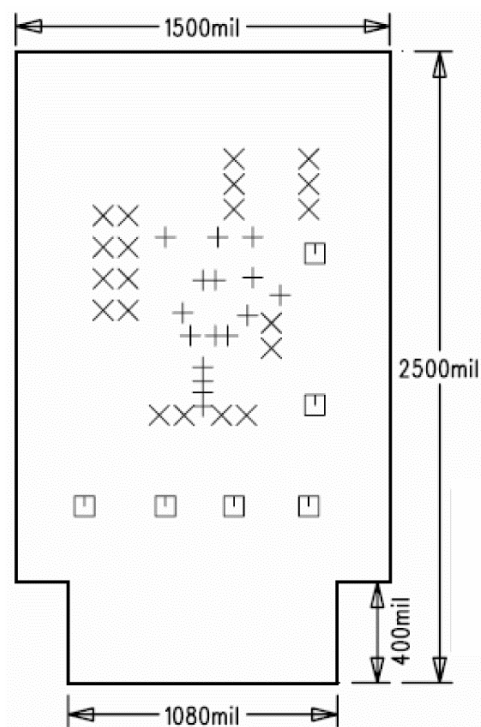


Top Layer



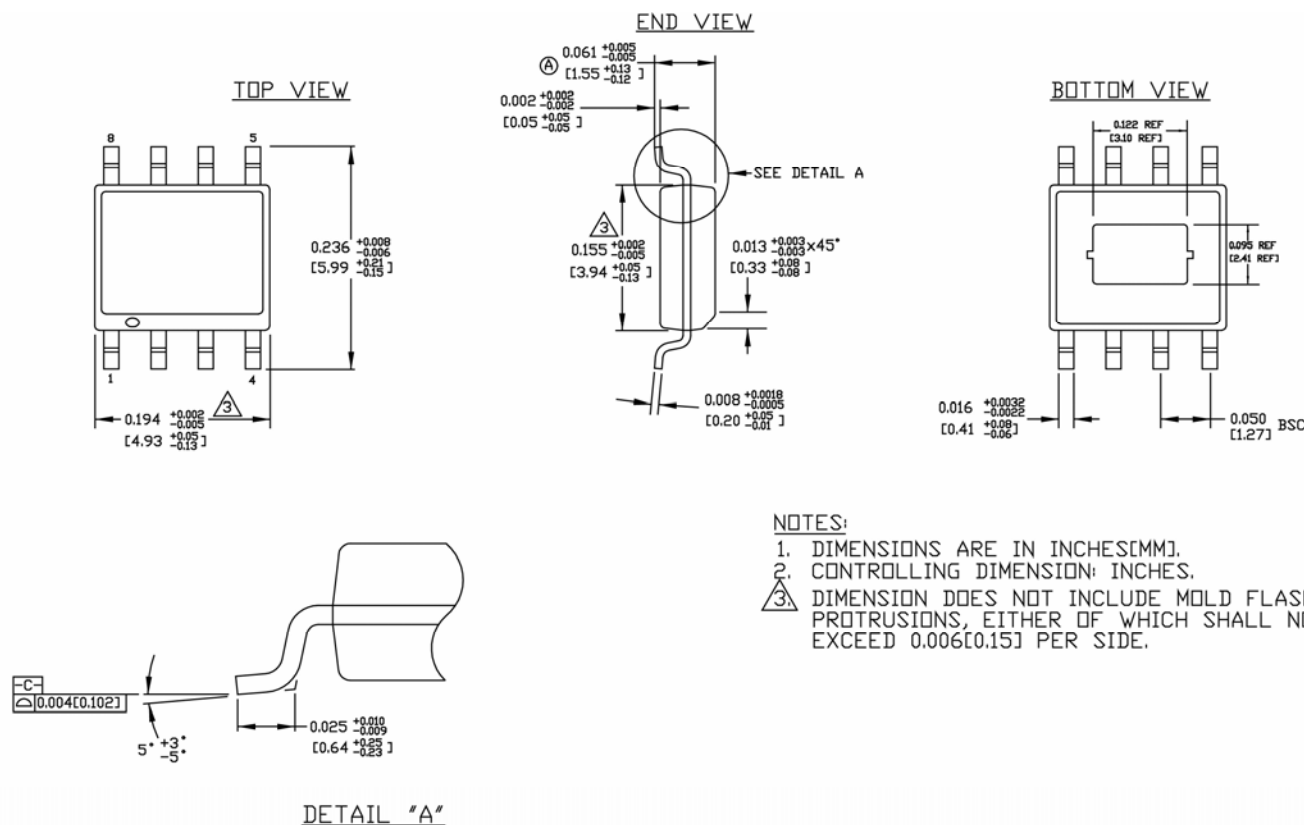
Bottom Layer

## PCB Evaluation Board Layout (Continued)



**Evaluation Board Dimensions**

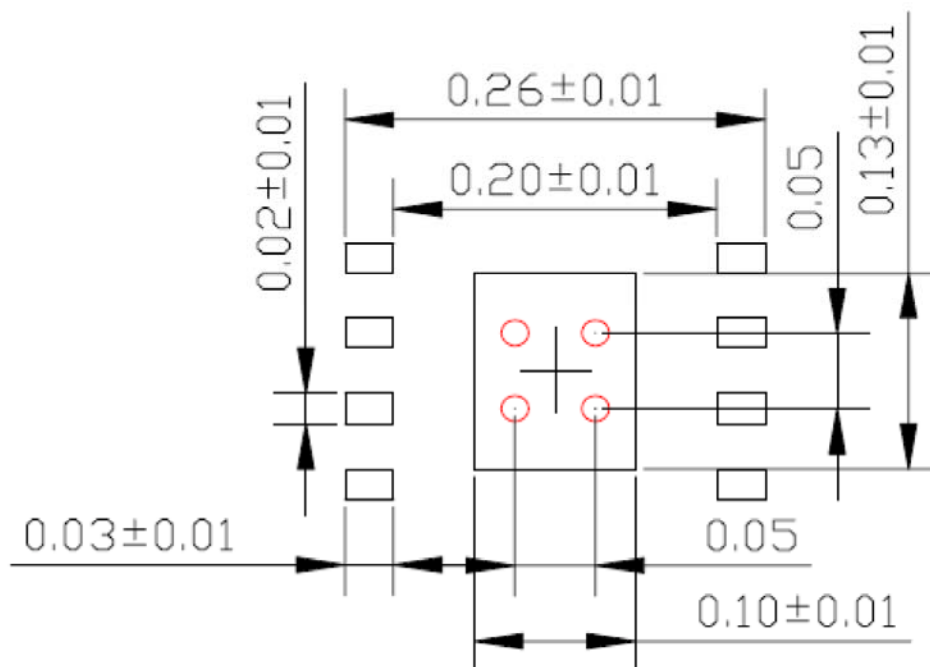
## Package Information



8-Pin Exposed Pad SOIC (ME)

## Recommended Land Pattern

LP # SOICNEP-8LD-LP-1  
 All units are in inches  
 Tolerance  $\pm 0.05$  if not noted



A red circle indicates a Thermal Via. Size should be .015-.017 inches in diameter and it should be connected to GND plane for maximum thermal performance.

### 8-Pin Exposed Pad SOIC

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 TEL +1 (408) 944-0800 FAX +1 (408) 474-1000 WEB <http://www.micrel.com>

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